N-Channel Enhancement Mode Field Effect Transistor

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- These Devices are Pb-Free and are RoHS Compliant
- ESD HBM = 1000 V as per JESD22 A114 and ESD CDM = 1500 V as per JESD22 C101

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

			,
Rating	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	60	V
Gate-Source Voltage	V _{GSS}	±20	V
$\begin{array}{ll} \mbox{Maximum Drain Current} & \mbox{Continuous} \\ T_J = 100^\circ \mbox{C} \\ \mbox{Pulsed} \end{array}$	Ι _D	310 195 1.2	mA mA A
Operating Junction Temperature Range	TJ	–55 to +150	°C
Storage Temperature Range	T _{STG}	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Total Device Dissipation Derating above $T_A = 25^{\circ}C$	PD	300 2.4	mW mW/°C
Thermal Resistance, Junction to Ambient*	R_{\thetaJA}	410	°C/W

*Device mounted on FR-4 PCB, 1" x 0.85" x 0.062". Minimum land pad size



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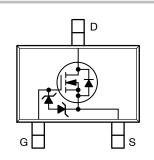
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MARKING DIAGRAM



7KW = Specific Device Marking



ORDERING INFORMATION[†]

Device	Package	Shipping [†]
2N7002KW	SC-70	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = $25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I _D = 10 μ A	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current		-	_	1.0 0.5	μA mA
I _{GSS}	Gate-Body Leakage	V _{DS} = 0 V, V _{GS} = ±20 V	-	-	±10	μA

ON CHARACTERISTICS (Note 1)

V _{GS(th)}	Gate Threshold Voltage	$V_{DS}=V_{GS},I_{D}=250\;\mu\text{A}$	1.1	-	2.1	V
R _{DS(on)}	Static Drain-Source On-Resistance	$ \begin{array}{l} V_{GS} = 10 \text{ V, } I_D = 500 \text{ mA} \\ V_{GS} = 10 \text{ V, } I_D = 500 \text{ mA}, T_J = 100^\circ\text{C} \\ V_{GS} = 5 \text{ V, } I_D = 50 \text{ mA} \\ V_{GS} = 5 \text{ V, } I_D = 50 \text{ mA}, T_J = 100^\circ\text{C} \end{array} $	_	_	1.6 2.4 2 3	Ω
V _{DS(on)}	Drain-Source On-Voltage	V_{GS} = 10 V, I_{D} = 500 mA V_{GS} = 5 V, I_{D} = 50 mA	_	-	3.75 1.5	V
I _{D(on)}	On-State Drain Current	V_{GS} = 10 V, V_{DS} = 2 V	500	_	_	mA
9 _{FS}	Forward Transconductance	$V_{DS} = 2 \text{ V}, \text{ I}_{D} = 0.2 \text{ A}$	80	-	-	mS

DYNAMIC CHARACTERISTICS

C _{iss}	Input Capacitance	V_{DS} = 25 V, V_{GS} = 0 V, f = 1.0 MHz	-	-	50	pF
C _{oss}	Output Capacitance		-	-	25	pF
C _{rss}	Reverse Transfer Capacitance		-	-	5	pF

SWITCHING CHARACTERISTICS

t _{d(on)}	Turn-On Delay Time	$V_{DD} = 30 \text{ V}, \text{ R}_{L} = 150 \Omega, \text{ V}_{GS} = 10 \text{ V},$	-	-	20	ns
t _{d(off)}	Turn-Off Delay Time	I _D = 200 mA, R _{GEN} = 25 Ω	-	-	60	ns

DRAIN-SOURCE DIODE CHARACTERISTICS

I _S	Maximum Continuous Drain-Source Diode Forward Current		-	115	mA
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		-	0.8	А
V _{SD}	Drain-Source Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_S = 115 \text{ mA}$		-	1.1	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1. Pulse Test: Pulse Width < 300 μs, Duty Cycle < 2.0%.

TYPICAL PERFORMANCE CHARACTERISTICS

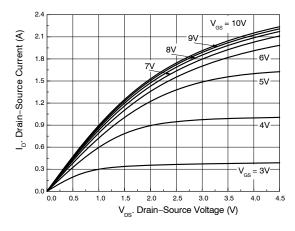


Figure 1. On–Region Characteristics

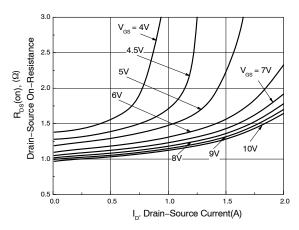


Figure 3. On–Resistance Variation with Gate Voltage and Drain Current

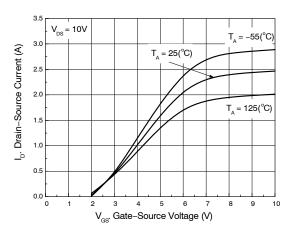


Figure 5. Transfer Characteristics

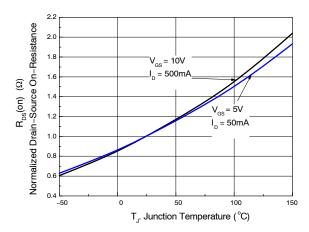


Figure 2. On–Resistance Variation with Temperature

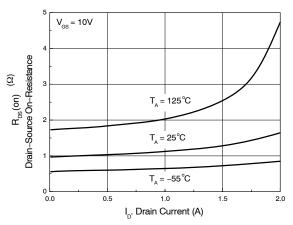
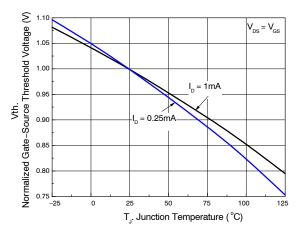
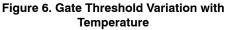


Figure 4. On-Resistance Variation with Drain Current and Temperature





TYPICAL PERFORMANCE CHARACTERISTICS

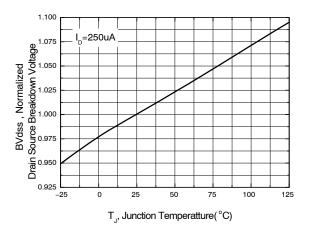


Figure 7. Breakdown Voltage Variation with Temperature

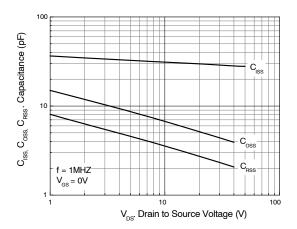


Figure 9. Capacitance Variation

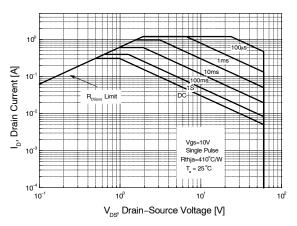
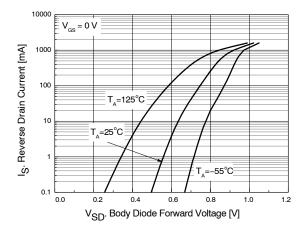


Figure 11. Maximum Safe Operating Area





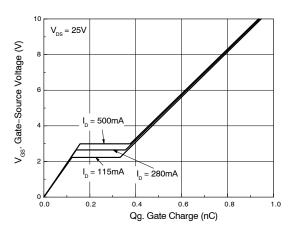


Figure 10. Gate Charge Characteristics

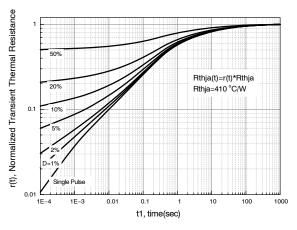
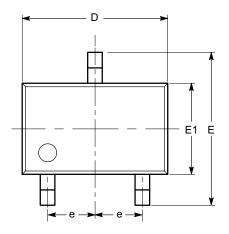


Figure 12. Transient Thermal Response Curve



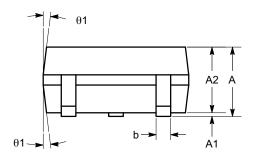
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SYMBOL	MIN	NOM	МАХ
Α	0.80		1.10
A1	0.00		0.10
A2	0.80	0.90	1.00
b	0.15		0.30
с	0.08		0.22
D	1.80	2.00	2.20
E	1.80	2.10	2.40
E1	1.15	1.25	1.35
е		0.65 BSC	
L	0.26	0.36	0.46
L1		0.42 REF	
L2		0.15 BSC	
θ	0°		8°
θ1	4°		10°

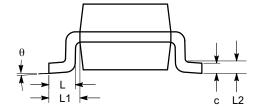




Notes:

(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC MO-203.

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